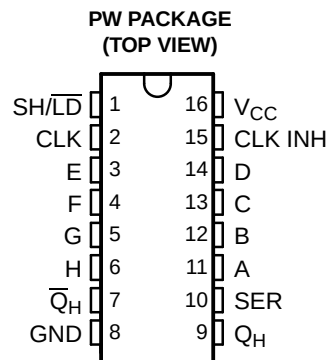


FEATURES

- **Controlled Baseline**
 - One Assembly/Test Site, One Fabrication Site
 - **Extended Temperature Performance of –55°C to 125°C**
 - **Enhanced Diminishing Manufacturing Sources (DMS) Support**
 - **Enhanced Product-Change Notification**
 - **Qualification Pedigree ⁽¹⁾**
 - **2-V to 5.5-V V_{CC} Operation**
 - **Max t_{pd} of 10.5 ns at 5 V**
 - **Supports Mixed-Mode Voltage Operation on All Ports**
 - **I_{off} Supports Partial-Power-Down Mode Operation**
 - **Latch-Up Performance Exceeds 250 mA Per JESD 17**
 - **ESD Protection Exceeds JESD 22**
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- (1) Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.



DESCRIPTION

The SN74LV165A-EP is a parallel-load, 8-bit shift register designed for 2-V to 5.5-V V_{CC} operation.

When the device is clocked, data is shifted toward the serial output Q_H . Parallel-in access to each stage is provided by eight individual direct data inputs that are enabled by a low level at the shift/load ($SH/\overline{LD}$) input. The SN74LV165A-EP features a clock-inhibit function and a complemented serial output, $\overline{Q}_H$.

Clocking is accomplished by a low-to-high transition of the clock (CLK) input while $SH/\overline{LD}$ is held high and clock inhibit (CLK INH) is held low. The functions of CLK and CLK INH are interchangeable. Since a low CLK and a low-to-high transition of CLK INH accomplishes clocking, CLK INH should be changed to the high level only while CLK is high. Parallel loading is inhibited when $SH/\overline{LD}$ is held high. The parallel inputs to the register are enabled while $SH/\overline{LD}$ is held low, independently of the levels of CLK, CLK INH, or SER.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the devices when they are powered down.

ORDERING INFORMATION

T_A	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–55°C to 125°C	TSSOP – PW	Reel of 2000	SN74LV165AMPWREP	LV165EP

- (1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



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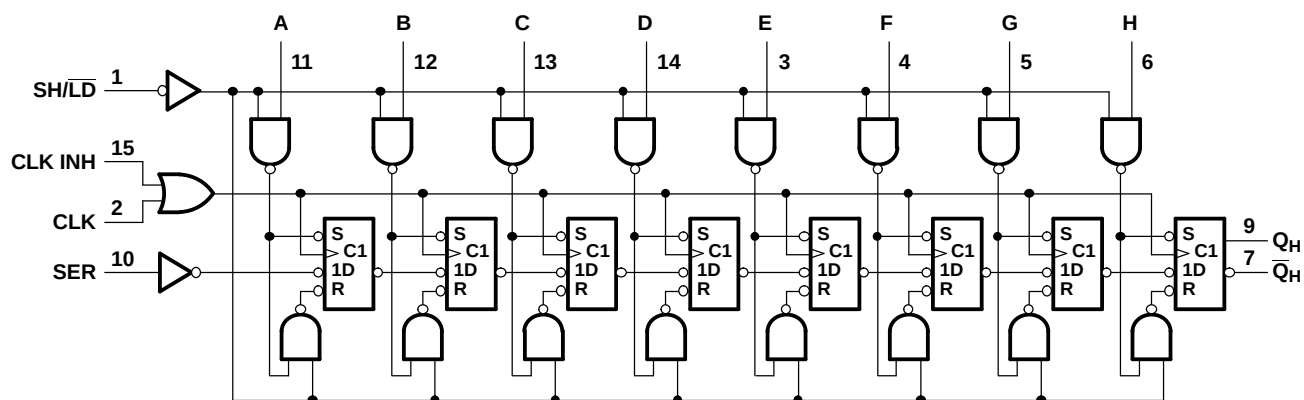
SN74LV165A-EP PARALLEL-LOAD 8-BIT SHIFT REGISTER

SCLS694–JANUARY 2006

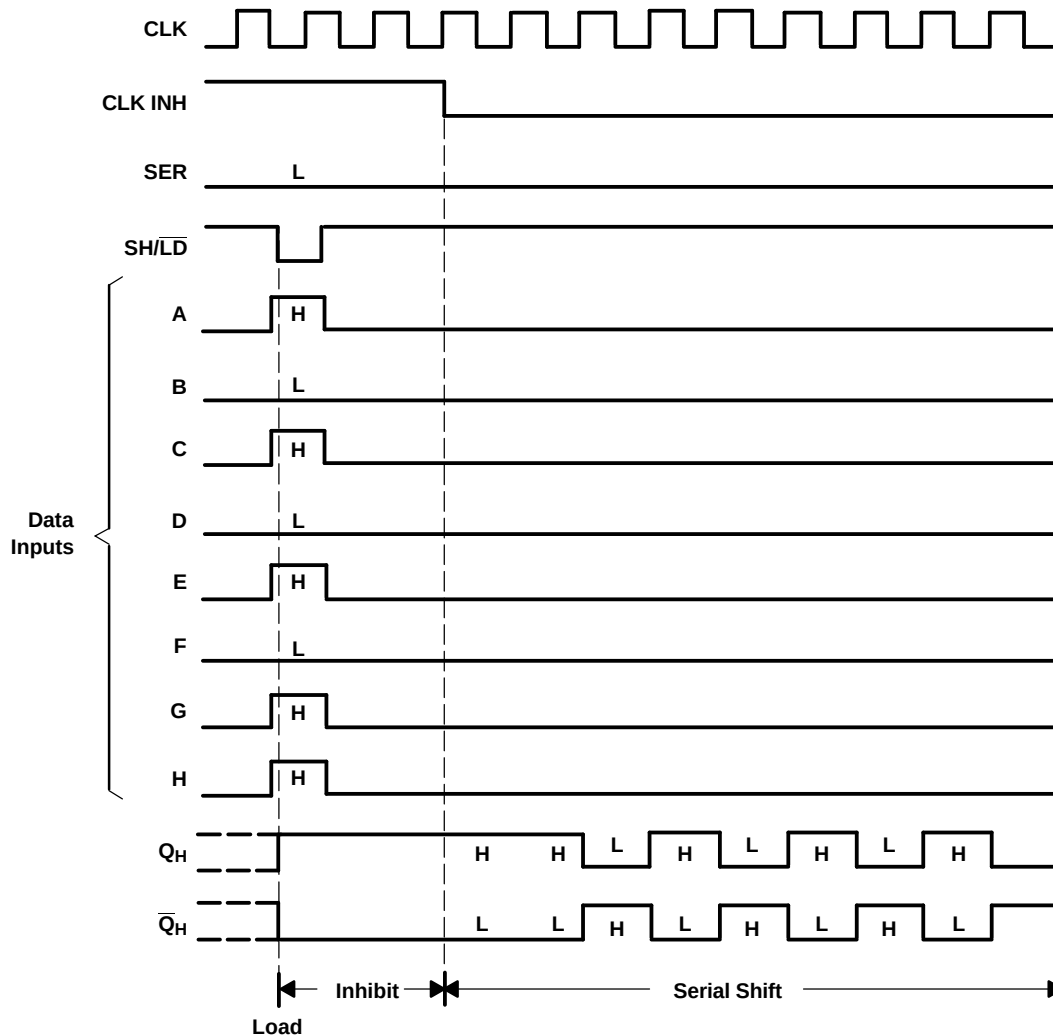
FUNCTION TABLE

INPUTS			OPERATION
SH/ $\overline{\text{LD}}$	CLK	CLK INH	
L	X	X	Parallel load
H	H	X	Q_0
H	X	H	Q_0
H	L	$\uparrow$	Shift
H	$\uparrow$	L	Shift

LOGIC DIAGRAM (POSITIVE LOGIC)



TYPICAL SHIFT, LOAD, AND INHIBIT SEQUENCES



SN74LV165A-EP

PARALLEL-LOAD 8-BIT SHIFT REGISTER

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Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT
V_{CC}	Supply voltage range	–0.5	7	V
V_I	Input voltage range ⁽²⁾	–0.5	7	V
V_O	Voltage range applied to any output in the high-impedance or power-off state ⁽²⁾	–0.5	7	V
V_O	Output voltage range ⁽²⁾⁽³⁾	–0.5	$V_{CC} + 0.5$	V
I_{IK}	Input clamp current	$V_I < 0$	–20	mA
I_{OK}	Output clamp current	$V_O < 0$	–50	mA
I_O	Continuous output current	$V_O = 0$ to V_{CC}	±25	mA
	Continuous current through V_{CC} or GND		±50	mA
θ_{JA}	Package thermal impedance ⁽⁴⁾		108	°C/W
T_{stg}	Storage temperature range	–65	150	°C

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

(3) This value is limited to 5.5 V maximum.

(4) The package thermal impedance is calculated in accordance with JESD 51-7.

Recommended Operating Conditions⁽¹⁾

		MIN	MAX	UNIT
V_{CC}	Supply voltage	2	5.5	V
V_{IH}	High-level input voltage	$V_{CC} = 2$ V	1.5	V
		$V_{CC} = 2.3$ V to 2.7 V	$V_{CC} \times 0.7$	
		$V_{CC} = 3$ V to 3.6 V	$V_{CC} \times 0.7$	
		$V_{CC} = 4.5$ V to 5.5 V	$V_{CC} \times 0.7$	
V_{IL}	Low-level input voltage	$V_{CC} = 2$ V	0.5	V
		$V_{CC} = 2.3$ V to 2.7 V	$V_{CC} \times 0.3$	
		$V_{CC} = 3$ V to 3.6 V	$V_{CC} \times 0.3$	
		$V_{CC} = 4.5$ V to 5.5 V	$V_{CC} \times 0.3$	
V_I	Input voltage	0	5.5	V
V_O	Output voltage	0	V_{CC}	V
I_{OH}	High-level output current	$V_{CC} = 2$ V	–50	µA
		$V_{CC} = 2.3$ V to 2.7 V	–2	mA
		$V_{CC} = 3$ V to 3.6 V	–6	
		$V_{CC} = 4.5$ V to 5.5 V	–12	
I_{OL}	Low-level output current	$V_{CC} = 2$ V	50	µA
		$V_{CC} = 2.3$ V to 2.7 V	2	mA
		$V_{CC} = 3$ V to 3.6 V	6	
		$V_{CC} = 4.5$ V to 5.5 V	12	
$\Delta t/\Delta v$	Input transition rise or fall rate	$V_{CC} = 2.3$ V to 2.7 V	200	ns/V
		$V_{CC} = 3$ V to 3.6 V	100	
		$V_{CC} = 4.5$ V to 5.5 V	20	
T_A	Operating free-air temperature	–55	125	°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	MIN	TYP	MAX	UNIT
V _{OH}	I _{OH} = –50 µA	2 V to 5.5 V	V _{CC} – 0.1			V
	I _{OH} = –2 mA	2.3 V	2			
	I _{OH} = –6 mA	3 V	2.48			
	I _{OH} = –12 mA	4.5 V	3.8			
V _{OL}	I _{OL} = 50 µA	2 V to 5.5 V			0.1	V
	I _{OL} = 2 mA	2.3 V			0.4	
	I _{OL} = 6 mA	3 V			0.44	
	I _{OL} = 12 mA	4.5 V			0.55	
I _I	V _I = 5.5 V or GND	0 to 5.5 V			±1	µA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	5.5 V			20	µA
I _{off}	V _I or V _O = 0 to 5.5 V	0			5	µA
C _i	V _I = V _{CC} or GND	3.3 V		1.7		pF

Timing Requirements

over recommended operating free-air temperature range, V_{CC} = 2.5 V ± 0.2 V (unless otherwise noted) (see [Figure 1](#))

			T _A = 25°C		MIN	MAX	UNIT
			MIN	MAX			
t _w	Pulse duration	CLK high or low	8.5		9		ns
		SH/ $\overline{\text{LD}}$ low	11		13		
t _{su}	Setup time	SH/ $\overline{\text{LD}}$ high before CLK↑	7		8.5		ns
		SER before CLK↑	8.5		9.5		
		CLK INH before CLK↑	7		7		
		Data before SH/ $\overline{\text{LD}}$ ↑	11.5		12		
t _h	Hold time	SER data after CLK↑	–1		0		ns
		Parallel data after SH/ $\overline{\text{LD}}$ ↑	0		0.5		
		SH/ $\overline{\text{LD}}$ high after CLK↑	0		0		

Timing Requirements

over recommended operating free-air temperature range, V_{CC} = 3.3 V ± 0.3 V (unless otherwise noted) (see [Figure 1](#))

			T _A = 25°C		MIN	MAX	UNIT
			MIN	MAX			
t _w	Pulse duration	CLK high or low	6		7		ns
		SH/ $\overline{\text{LD}}$ low	7.5		9		
t _{su}	Setup time	SH/ $\overline{\text{LD}}$ high before CLK↑	5		6		ns
		SER before CLK↑	5		6		
		CLK INH before CLK↑	5		5		
		Data before SH/ $\overline{\text{LD}}$ ↑	7.5		8.5		
t _h	Hold time	SER data after CLK↑	0		0		ns
		Parallel data after SH/ $\overline{\text{LD}}$ ↑	0.5		0.5		
		SH/ $\overline{\text{LD}}$ high after CLK↑	0		0		

SN74LV165A-EP PARALLEL-LOAD 8-BIT SHIFT REGISTER

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Timing Requirements

over recommended operating free-air temperature range, $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted) (see [Figure 1](#))

			$T_A = 25^\circ\text{C}$		MIN	MAX	UNIT
			MIN	MAX			
t_w	Pulse duration	CLK high or low	4		6.5		ns
		SH/ $\overline{\text{LD}}$ low	5		6.5		
t_{su}	Setup time	SH/ $\overline{\text{LD}}$ high before CLK $\uparrow$	4		4		ns
		SER before CLK $\uparrow$	4		4		
		CLK INH before CLK $\uparrow$	3.5		4.5		
		Data before SH/ $\overline{\text{LD}}$ $\uparrow$	5		5		
t_h	Hold time	SER data after CLK $\uparrow$	0.5		0.5		ns
		Parallel data after SH/ $\overline{\text{LD}}$ $\uparrow$	1		1		
		SH/ $\overline{\text{LD}}$ high after CLK $\uparrow$	0.5		0.5		

Switching Characteristics

over recommended operating free-air temperature range, $V_{CC} = 2.5\text{ V} \pm 0.2\text{ V}$ (unless otherwise noted) (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			MIN	MAX	UNIT
				MIN	TYP	MAX			
f_{max}			$C_L = 50\text{ pF}$	40	65		35		MHz
t_{pd}	CLK	Q_H or $\overline{Q}_H$	$C_L = 50\text{ pF}$		15.3	23.3	1	26	ns
	SH/ $\overline{\text{LD}}$				16.1	25.1	1	28	
	H				15.9	25.3	1	28	

Switching Characteristics

over recommended operating free-air temperature range, $V_{CC} = 3.3\text{ V} \pm 0.3\text{ V}$ (unless otherwise noted) (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			MIN	MAX	UNIT
				MIN	TYP	MAX			
f_{max}			$C_L = 50\text{ pF}$	60	90		50		MHz
t_{pd}	CLK	Q_H or $\overline{Q}_H$	$C_L = 50\text{ pF}$		10.9	14.9	1	16.9	ns
	SH/ $\overline{\text{LD}}$				11.3	19.3	1	22	
	H				11.1	17.6	1	20	

Switching Characteristics

over recommended operating free-air temperature range, $V_{CC} = 5\text{ V} \pm 0.5\text{ V}$ (unless otherwise noted) (see [Figure 1](#))

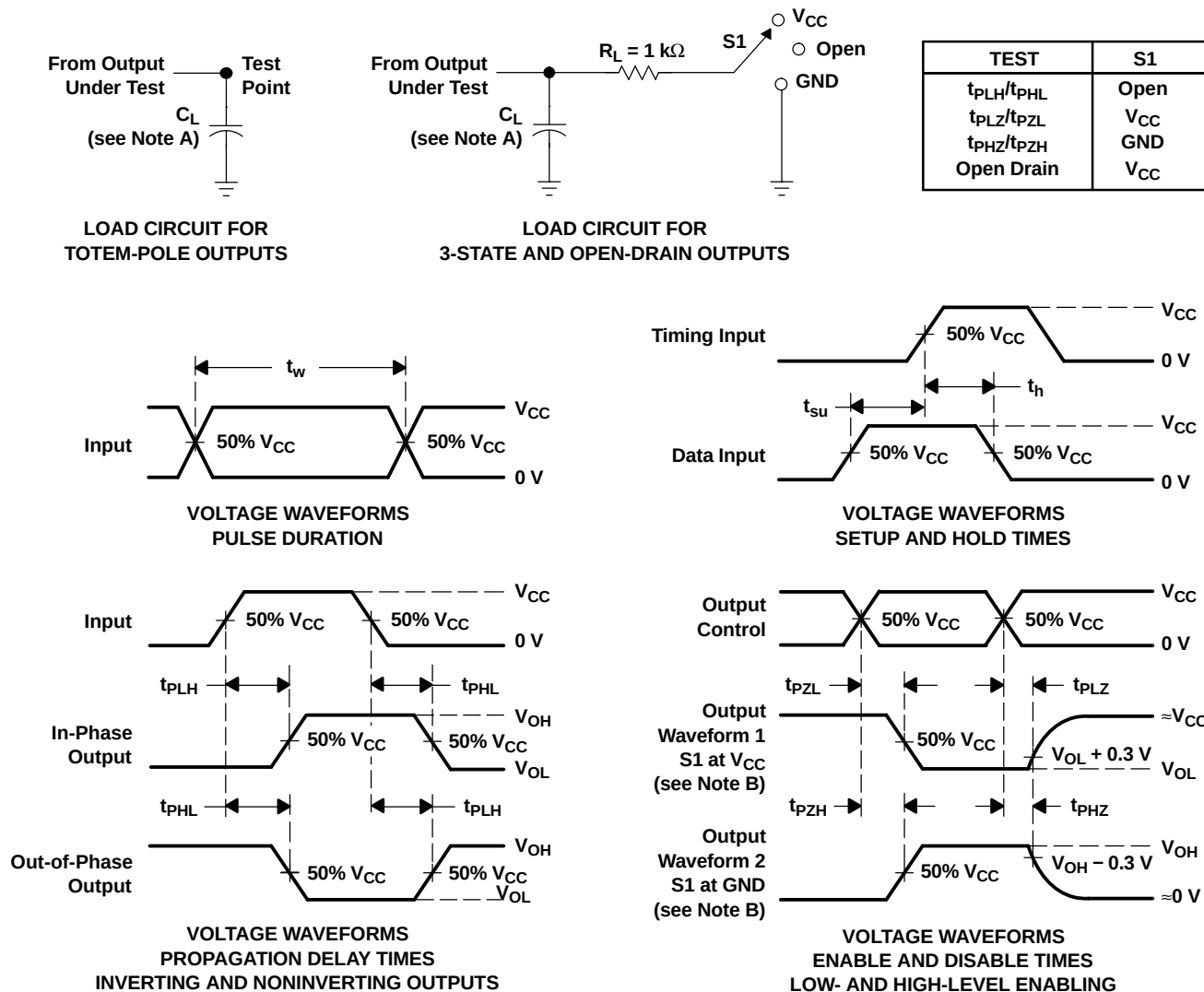
PARAMETER	FROM (INPUT)	TO (OUTPUT)	LOAD CAPACITANCE	$T_A = 25^\circ\text{C}$			MIN	MAX	UNIT
				MIN	TYP	MAX			
f_{max}			$C_L = 50\text{ pF}$	75	85		75		MHz
t_{pd}	CLK	Q_H or $\overline{Q}_H$	$C_L = 50\text{ pF}$		7.7	11.9	1	13.5	ns
	SH/ $\overline{\text{LD}}$				7.7	11.9	1	13.5	
	H				7.6	11	1	12.5	

Operating Characteristics

$T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS		V_{CC}	TYP	UNIT
C_{pd}	Power dissipation capacitance	$C_L = 50\text{ pF}$, $f = 10\text{ MHz}$		3.3 V	36.1	pF
				5 V	37.5	

PARAMETER MEASUREMENT INFORMATION



- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 1\text{ MHz}$, $Z_O = 50\ \Omega$, $t_r \leq 3\text{ ns}$, $t_f \leq 3\text{ ns}$.
 - D. The outputs are measured one at a time, with one input transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PHL} and t_{PLH} are the same as t_{pd} .
 - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuits and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LV165AMPWREP	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/06603-01XE	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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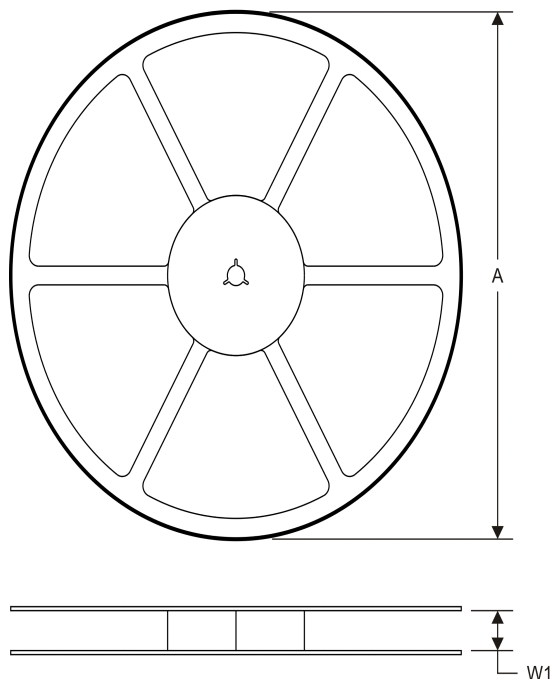
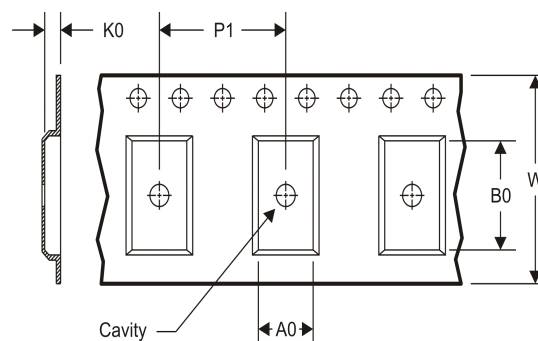
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OTHER QUALIFIED VERSIONS OF SN74LV165A-EP :

- Catalog: [SN74LV165A](#)

NOTE: Qualified Version Definitions:

- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


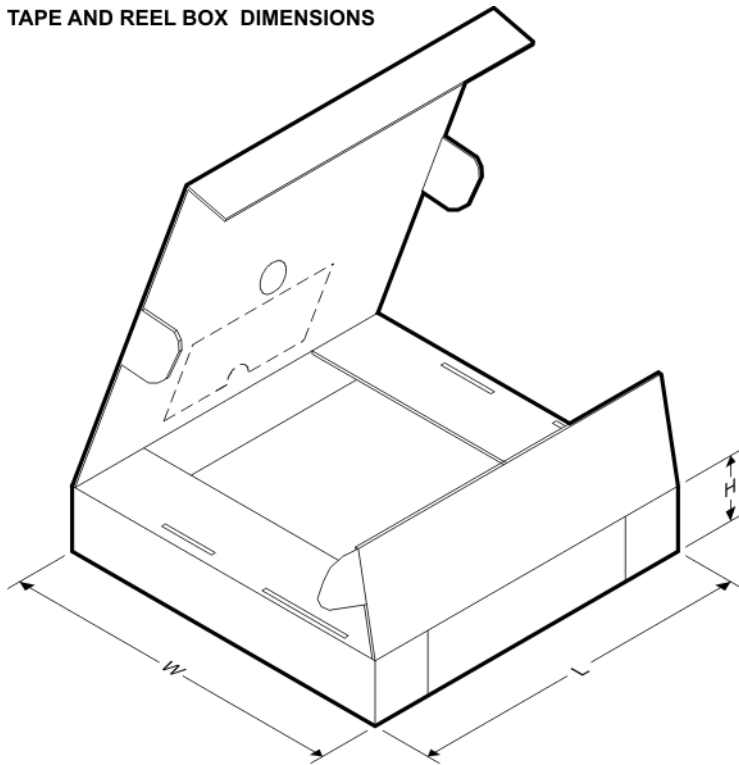
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV165AMPWREP	TSSOP	PW	16	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS

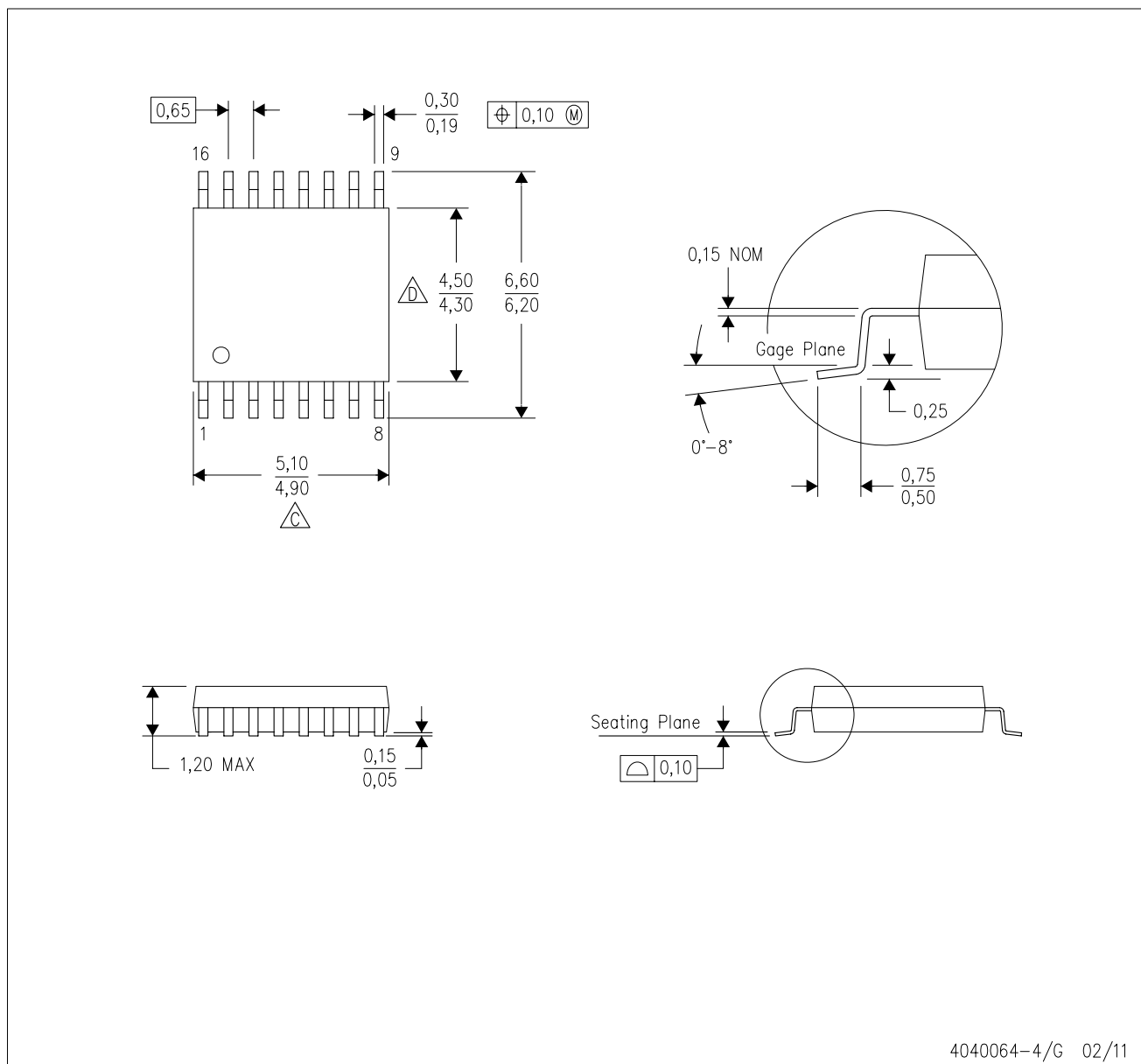


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV165AMPWREP	TSSOP	PW	16	2000	367.0	367.0	35.0

PW (R-PDSO-G16)

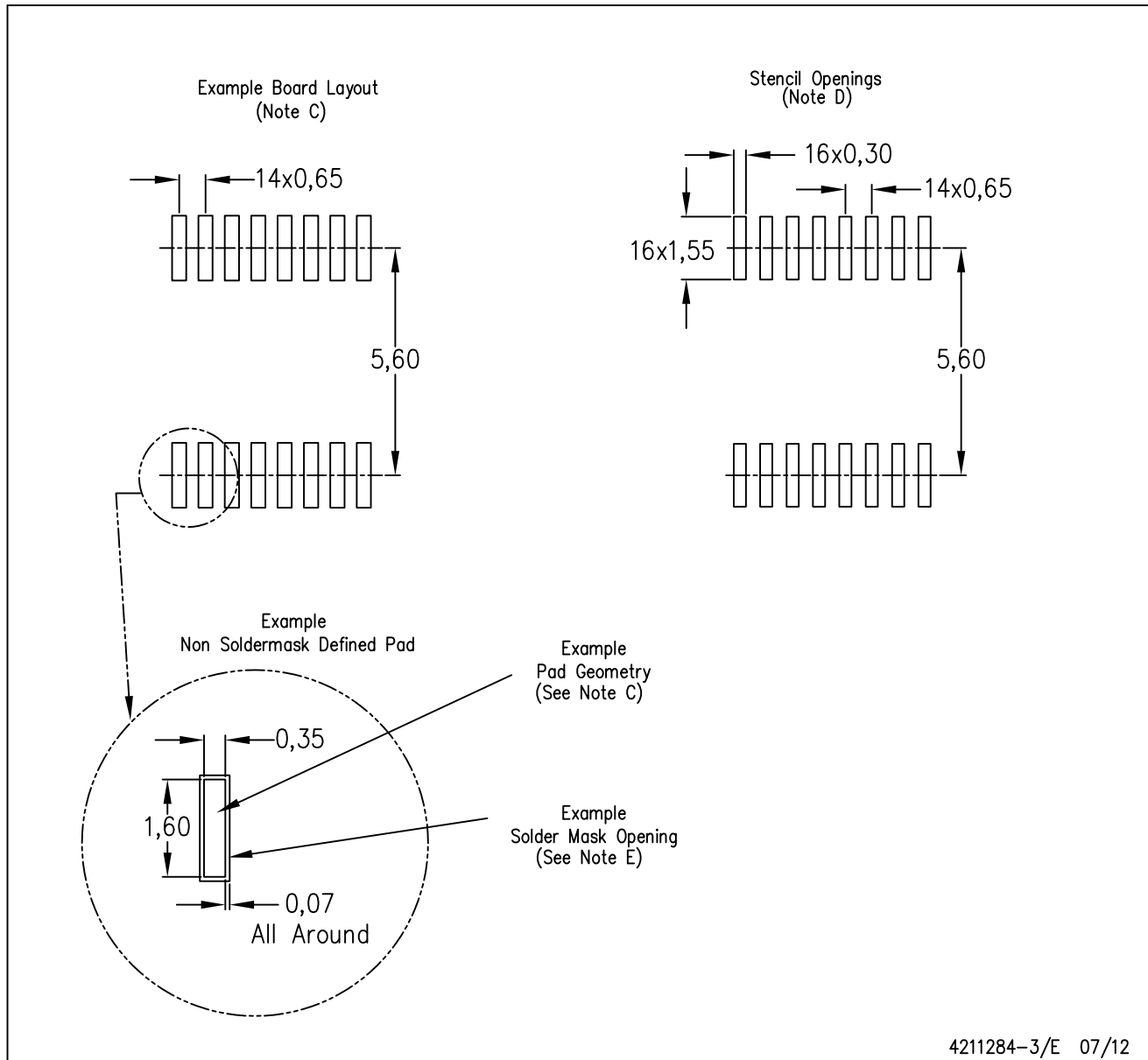
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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